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*Text and photograph available at: <http://www.congatec.com/press>*

**New Product Introduction**

congatec COM Express Computer-on-Modules with brand new
8th Gen Intel® Xeon® and Intel® Core™ processors (Coffee Lake H)

**Powerful congatec six-pack for Type 6**

**Deggendorf, Germany, 3 April 2018** **\* \* \*** congatec – a leading vendor of standardized and customized embedded computer boards and modules – introduces its brand new conga-TS370 COM Express Type 6 Computer-on-Modules in parallel with the launch of the 8th Generation Embedded Intel® Xeon® and Intel® Core™ processors (codename Coffee Lake H). They propel the 35-45 W TDP class of COM Express Type 6 modules to a new ‘six-pack’ level of high-end embedded computing, offering for the first time up to 6 cores, 12 threads and an impressive turbo boost of up to 4.4 GHz and drive up to three independent 4k UHD displays. Initial tests from congatec indicate that these brand new six-core modules offer between 45 to 50 percent more multi-thread and 15 to 25 percent more single-thread performance, compared to 7th Gen Intel® Core™ processor based variants. At a given TPD, system designs achieve higher bandwidth at overall lower power consumption ultimately leading to higher system efficiency. Target applications are high performance embedded and mobile systems, industrial and medical workstations, storage servers and cloud workstations, as well as media transcoding and edge computing cores.

“Markets such as medical imaging and Industry 4.0 as well as video analytics for e.g. situational awareness and transportation observation are keen on any new performance improvement,” explains Martin Danzer, Director of Product Management at congatec. “We simplify the use of these performance improvements with our standardized Computer-on-Modules, cooling solutions and eAPIs, making upgrading to the latest processor generations more or less a plug & play task.”

Beside performance gains, the new congatec modules impress with extended long-term availability of 10 years plus, high bandwidth I/Os with 4x USB 3.1 Gen 2 (10 Gbit/s) and Intel® Optane™ memory support, as well as enhanced security features including Intel® Software Guard extensions, Trusted Execution Engine and Intel® Platform Trust Technology.

**The feature set in detail**

The new conga-TS370 COM Express Basic Type 6 Computer-on-Modules are available with six-core Intel® Xeon® and Intel® Core™ i7 processors, or quad core Intel® Core™ i5 processors in a 35 to 45 W cTDP envelope and up to 32 GB DDR4 2666 memory with ECC option. The integrated Intel® UHD630 graphics supports up to three independent 4k displays with up to 60Hz via DP 1.4 , HDMI, eDP and LVDS. For the first time, designers can switch now from eDP to LVDS purely by software without any hardware change. The modules excel with high bandwidth I/Os including 4x USB 3.1 Gen 2 (10 Gbit/s), 8x USB 2.0 and 1x PEG and 8 PCIe Gen 3.0 lanes for powerful system extensions including Intel® Optane™ memory. All common Linux operating systems as well as the 64-bit versions of Microsoft Windows 10 and Windows 10 IoT are executable. A premium class personal integration support in combination with an extensive range of accessories as well as standardized or customized carrier boards and systems complete the new modules’ service package.

The new conga-TS370 COM Express Type 6 Computer-on-Modules can be ordered in the following standard configurations:

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| **Processor** |  | **Cores/Threads** |  | **Clock [GHz] (Base/Boost)**  |  | **Cache (MB)**  |  | **TDP / cTDP [W]**  |
| Intel® Xeon® E-2176M |  | 6 / 12 |  | 2.7 / 4.4 |  | 12 |  | 45 / 35 |
| Intel® Core™ i7-8850H |  | 6 / 12 |  | 2.6 / 4.3 |  | 9 |  | 45 / 35 |
| Intel® Core™ i5-8400H |  | 4 / 8 |  | 2.5 / 4.2 |  | 8 |  | 45 / 35 |

More information about the new conga-TS370 high-performance COM Express Type 6 Computer-on-Modules is available at: <http://www.congatec.com/en/products/com-express-type6/conga-ts370.html>

**About congatec**congatec is a leading supplier of industrial computer modules using the standard form factors COM Express, Qseven and SMARC as well as single board computers and customizing services. congatec’s products can be used in a variety of industries and applications, such as industrial automation, medical, entertainment, transportation, telecommunication, test & measurement and point-of-sale. Core knowledge and technical know-how includes unique extended BIOS features as well as comprehensive driver and board support packages. Following the design-in phase, customers are given support via extensive product lifecycle management. The company’s products are manufactured by specialist service providers in accordance with modern quality standards. Headquartered in Deggendorf, Germany, congatec currently has entities in USA, Taiwan, China, Japan and Australia as well as United Kingdom, France, and the Czech Republic. More information is available on our website at [www.congatec.com](http://www.congatec.com) or via [Facebook](http://www.facebook.com/Congatec), [Twitter](https://mobile.twitter.com/congatecAG) and [YouTube](http://www.youtube.com/congatecAE).

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